

L Number	Hits	Search Text	DB	Time stamp
1	18	hwang-yong-sup.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:54
2	50	chae-gee-sung.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:54
3	26	jo-gyoo-chul.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:54
4	64	hwang-yong-sup.in. chae-gee-sung.in. jo-gyoo-chul.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:54
5	4323	(349/39,42,43,46,139,147).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:55
6	2276	(257/59,72).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:55
8	1	(hwang-yong-sup.in. chae-gee-sung.in. jo-gyoo-chul.in.) and ((257/59,72).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 08:55
7	19	(hwang-yong-sup.in. chae-gee-sung.in. jo-gyoo-chul.in.) and ((349/39,42,43,46,139,147).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:19
9	154592	(gate scan\$4) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:19
10	84393	(gate scan\$4) adj (line wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:20
11	2388	(gate scan\$4) adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:20
12	1164870	copper cu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:22

13	12733	barrier adj metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:22
14	2223	(copper cu) near10 (barrier adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:22
17	3	((gate scan\$4) adj pad) near10 ((copper cu) near10 (barrier adj metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:24
16	3	((gate scan\$4) adj (line wire)) near10 ((copper cu) near10 (barrier adj metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:26
15	14	((gate scan\$4) adj electrode) near10 ((copper cu) near10 (barrier adj metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:28
18	55039	double-layer\$2 two-layer\$3 plural-layer\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
19	45103	drain adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
20	41511	source adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
21	2097	data adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
22	84742	data adj (line wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
23	358	(drain adj electrode) same (source adj electrode) same (data adj pad) same (data adj (line wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29
24	517	((gate scan\$4) adj electrode) same ((gate scan\$4) adj (line wire)) same ((gate scan\$4) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:29

25	214	((drain adj electrode) same (source adj electrode) same (data adj pad) same (data adj (line wire))) same (((gate scan\$4) adj electrode) same ((gate scan\$4) adj (line wire)) same ((gate scan\$4) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:30
26	13	((drain adj electrode) same (source adj electrode) same (data adj pad) same (data adj (line wire))) same (((gate scan\$4) adj electrode) same ((gate scan\$4) adj (line wire)) same ((gate scan\$4) adj pad))) same (double-layer\$2 two-layer\$3 plural-layer\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:33
27	224184	metal near10 (copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:34
28	3	((drain adj electrode) same (source adj electrode) same (data adj pad) same (data adj (line wire))) same (((gate scan\$4) adj electrode) same ((gate scan\$4) adj (line wire)) same ((gate scan\$4) adj pad))) same (metal near10 (copper cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:35
29	1134	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:35
30	176	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj (line wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:35
31	28	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
32	159	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 (drain adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
33	131	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 (source adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
34	21	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
35	124	(double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj (line wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
36	55	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36

37	59	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
38	64	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
39	27	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
40	11	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:36
41	3	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
42	32	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (drain adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
43	26	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (drain adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
44	31	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (source adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
45	17	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (source adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
46	9	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
47	2	((257/59,72).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37
48	38	((349/39,42,43,46,139,147).ccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:37

49	20	((257/59,72).cccls.) and ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:38
55	2	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:39
56	19	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (data adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:39
50	16	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:39
51	11	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj (line wire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:42
52	3	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 ((gate scan\$4) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:43
53	10	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (drain adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:43
54	6	(copper cu) same ((double-layer\$2 two-layer\$3 plural-layer\$2) near10 (source adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 09:45

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1	45138	double-layered plural-layer\$3 two-layer\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:38
2	689386	buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:39
3	498	((double-layered plural-layer\$3 two-layer\$3) same buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:39
4	33674	349\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:39
5	7	((double-layered plural-layer\$3 two-layer\$3) same buffer) and 349\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:42
6	283749	257\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:42
7	171	((double-layered plural-layer\$3 two-layer\$3) same buffer) and 257\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/11 12:42